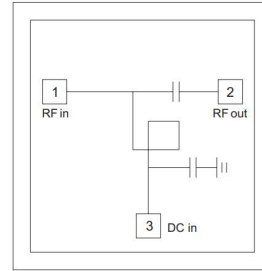


Performance

- Frequency: 18~40GHz
- Insertion loss: 0.5dB
- RF/DC Isolation: 20dB
- Input/Output Impedance: 50 Ohm
- Chip size: 0.9*0.88*0.1mm

Function Diagram

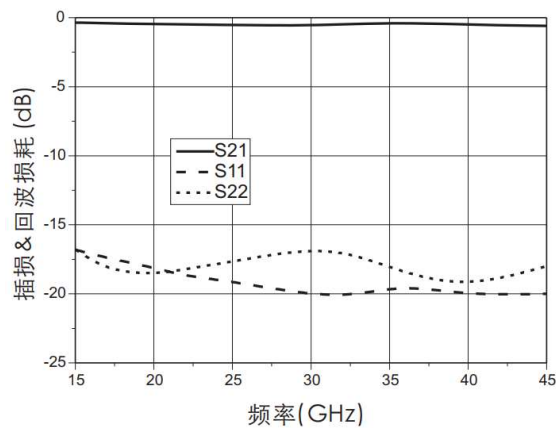


Electrical Specifications (Ta=+25°C, 50Ω system)

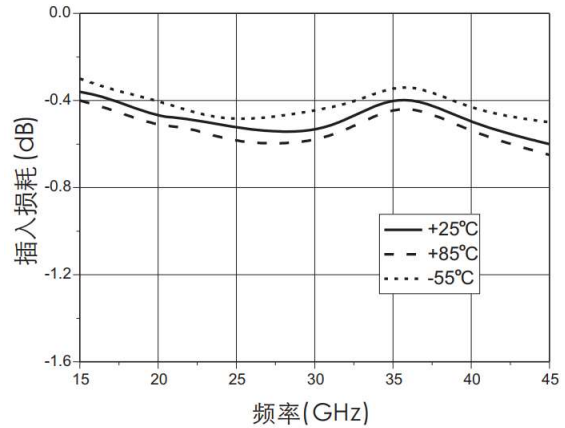
Parameter	Min	Typical	Max	Unit
Frequency Range	18~40			GHz
Insertion Loss	-	0.5	0.8	dB
Input Return loss	-	18	-	dB
Output Return loss	-	18	-	dB
RF/DC Isolation	20	30	-	dB

Test Curves (Die chip + Bonding line test)

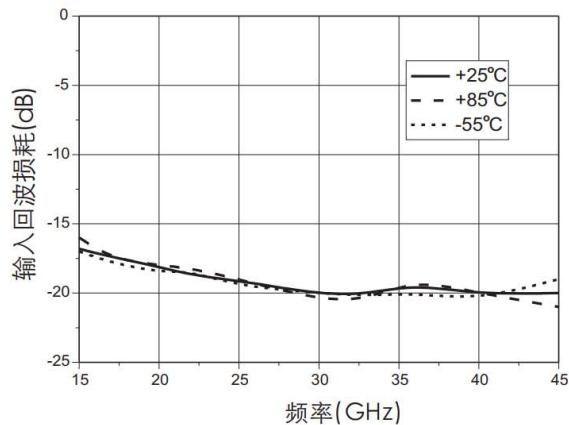
Insertion loss & Input/Output Return Loss



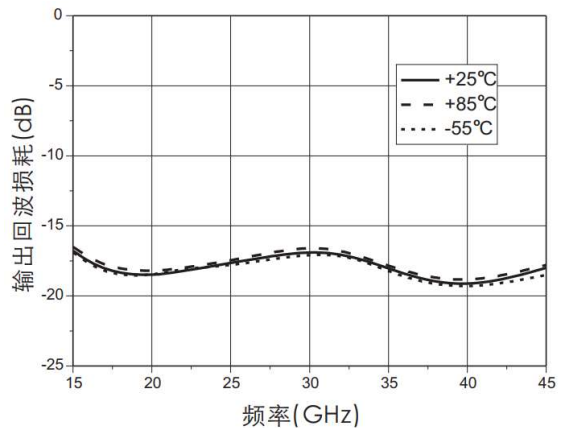
Insertion loss vs. Temperature



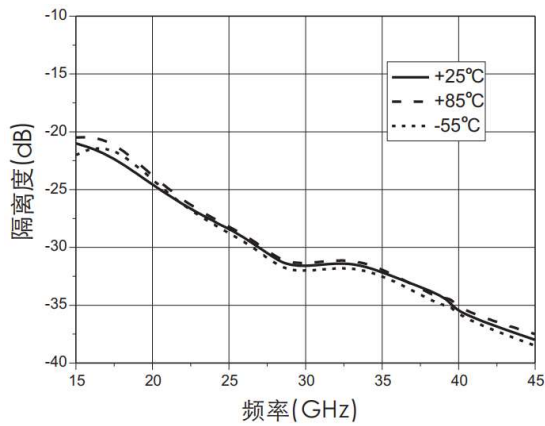
Input Return Loss vs. Temperature



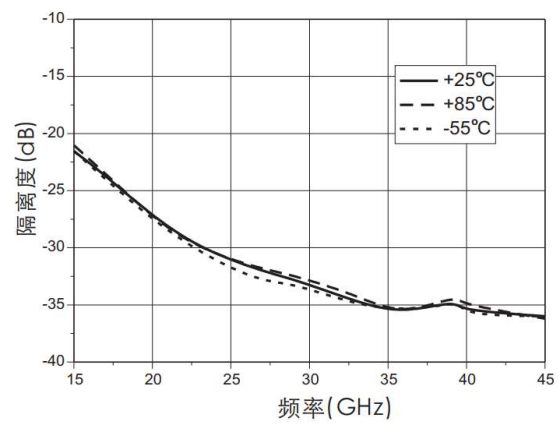
Output Return Loss vs. Temperature



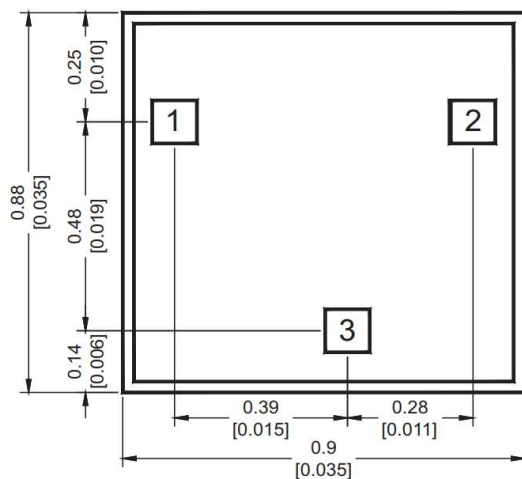
Port1,3 Isolation vs. Temperature



Port2,3 Isolation vs. Temperature



Outline Size



Note:

1. Unit: μm
2. Bottom side is gold plated
3. Bottom side is GND
4. Bonding pads is gold plated, size: $0.09 \times 0.1 \text{ mm}$
5. Don't bonding on thru holds
6. Tolerance: $\pm 50 \mu\text{m}$

Absolute Max Ratings

Max Input Power (W)	5
DC Current (mA)	200
Storage Temperature	-65 ~ +150°C
Operating Temperature	-55 ~ +125°C



ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS